

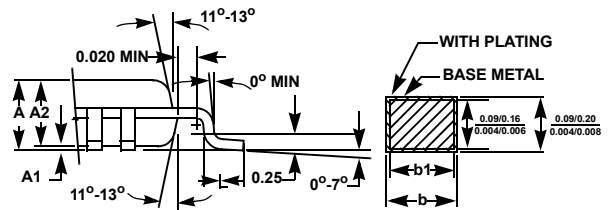
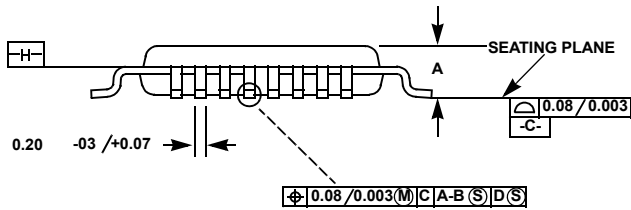
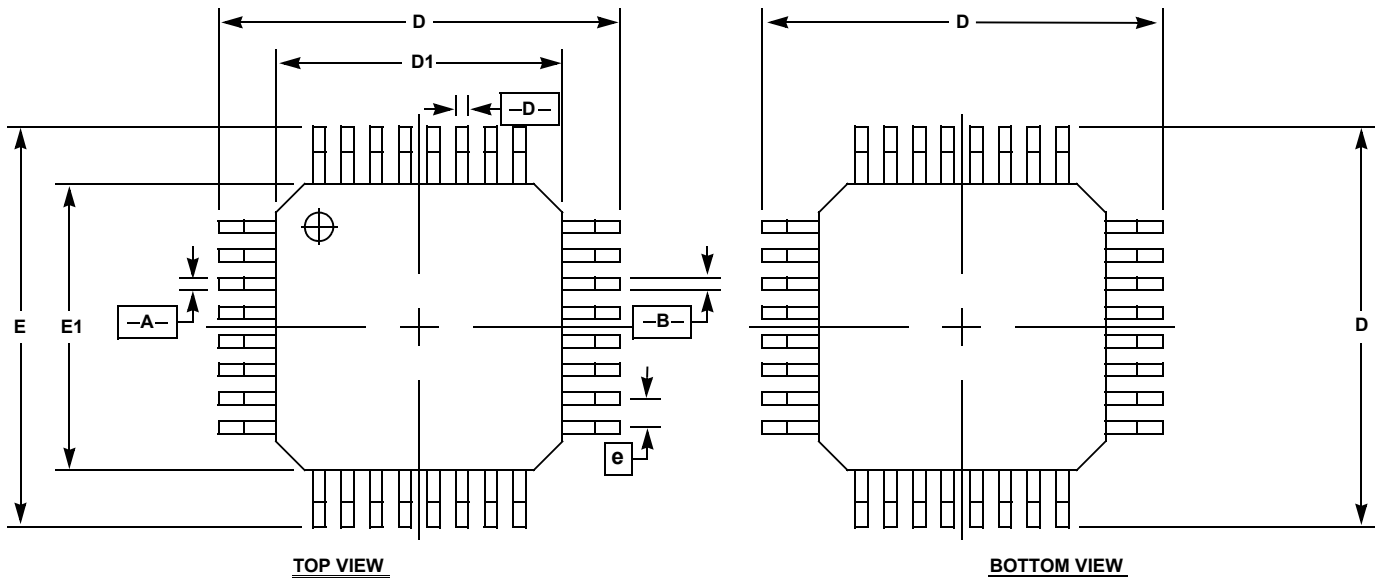
Plastic Packages for Integrated Circuits

Package Outline Drawing

Q32.5X5A

32 LEAD THIN PLASTIC QUAD FLATPACK PACKAGE (TQFP)

Rev 1, 10/11



SIDE VIEW

DETAIL "A"

SCALE NONE

SYMBOL	MIN	MAX	NOTES
A	-	1.13	-
A1	0.039	0.089	-
A2	0.95	1.05	-
b	0.17	0.27	6
b1	0.17	-0.23	-
D	7 BSC		-
E	7 BSC		-
D1	5 BSC		-
E1	5 BSC		-
e	0.5 BSC		-
L	0.45	0.75	-
N	32		6

NOTES:

1. Controlling Dimension; Millimeter, converted inch dimensions are not necessarily exact.
2. All dimensioning and tolerancing conform to ANSI Y14.5-1982.
3. Dimensions D and E to be determined at seating plane -C-
4. Dimensions D1 and E1 to be determined at datum plane -H-
5. Dimensions D1 and E1 do not include mold protusion. Allowable protusion is 0.25mm (0.010 inch) per side.
6. Dimension b does not include dambar protusion. Allowable dambar protusion shall not cause the lead width to exceed the maximum b dimensions by more than 0.08mm (0.003 inch).
7. "N" is the number of terminal position.

